

■ Features

- Molding Inductor.
- High reliability.
- High current, low DCR, high efficiency.
- Very low acoustic noise and very low leakage flux noise.
- Operating temperature:-55℃ ~ +125℃ (Including self-temperature rise) .

■ Applications

- General Electronic.
- Video Device,TV,TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server,VGA Card/Module.
- DC/DC converter.

■ Product Identification

YSPIT □□□□□ — □□□ □
 (1) (2) (3) (4)

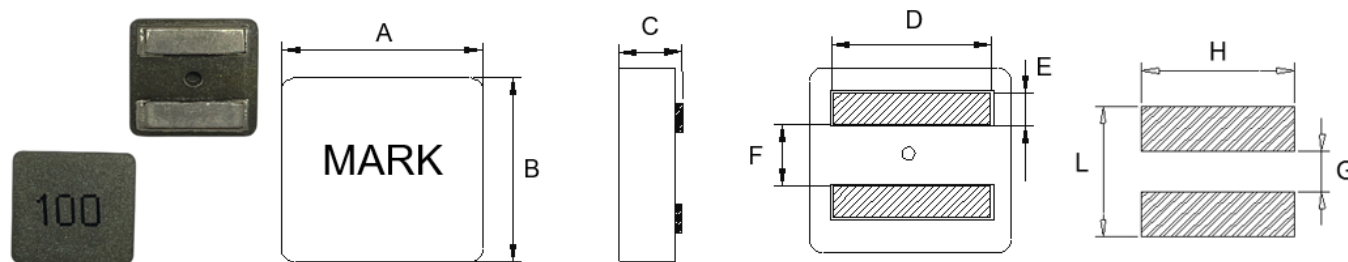
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N=±30%,M=±20%

■ Shapes and Dimensions (Unit: mm)



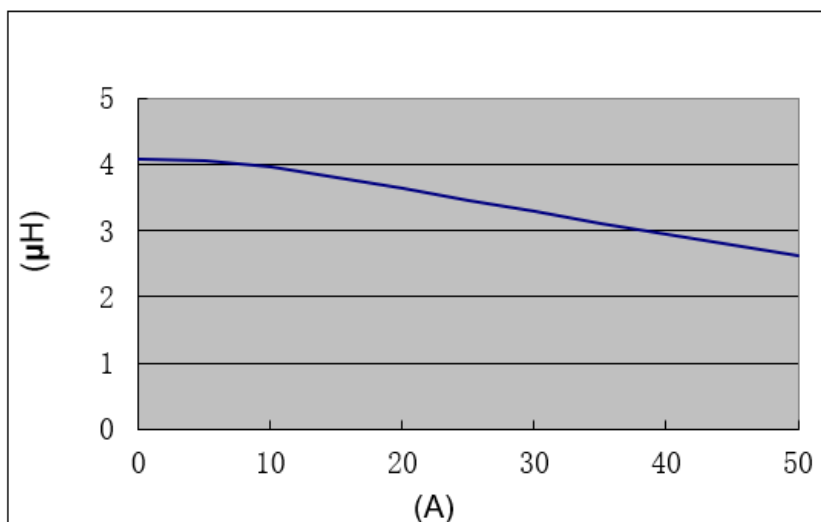
TYPE	A	B	C	D	E	F	G Ref.	H Ref.	L Ref.
YSPIT1508A	16.5±0.3	15.5±0.3	7.7±0.3	13.2±0.5	3.2±0.3	7.0±0.5	6.0	15.0	15.0

■ Electrical Characteristics

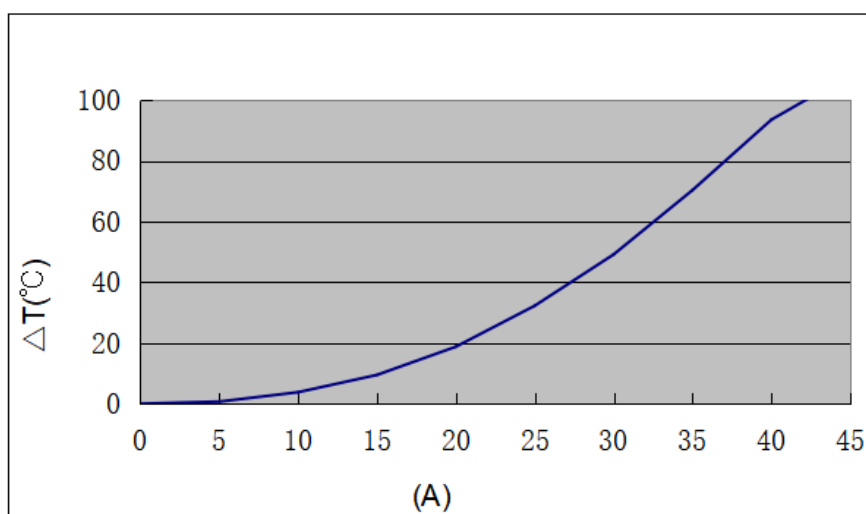
Part Number	Inductance (μH)	Test conditions	DCR Max. (mΩ)	Isat Typ. (A)	Irms Typ. (A)
YSPIT1508A-4R7M	4.7±20%	100KHz/0.1V	5.2	32.0	26.5

- ※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 25°C)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40°C. (at 25°C).
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.
- ※ Storage temperature and humidity range (product with tapping):-10°C~+40°C,RH70% Max.
- ※ Absolute maximum voltage 30VDC.

■ Current Value VS Inductance Value Curve



■ Current Value VS Temperature Curve



■ Mechanical Reliability

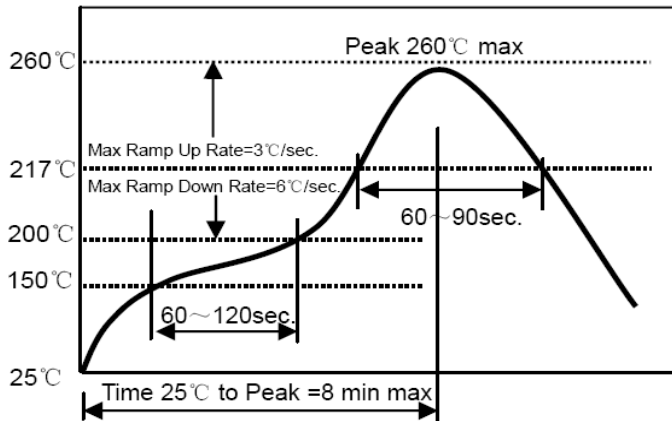
Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in visual 2. New solder coverage More than 95%	1.Preheat: 155℃±5℃ , 60S±2S 2.Tin: lead-free. 3.Temperature:240℃±5℃, flux 3.0S±0.5S.
Mechanical shock	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Acceleration: 100G 2. Pulse time: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Reflow: 2times 2. Frequency: 10HZ ~ 50HZ ~ 10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm±10% 4. Directions: X,Y,Z 5. Time: 12 cycle / direction

■ Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. First -55℃ for 30 minutes, last 125℃ for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 3 minutes. 3. Measured at room temperature after placing for 24±2 hours
Biased Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1.Reflow 2 times, 2.85℃±3℃,85%±3%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours
Low temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature: -55 $\pm 2^\circ\text{C}$ 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours
High temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature: +125 $\pm 2^\circ\text{C}$ 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours

■ Recommended Soldering Technologies

Re-flowing Profile



Preheat condition: 150 ~200°C/60~120sec.

Allowed time above 217°C: 60~90sec.

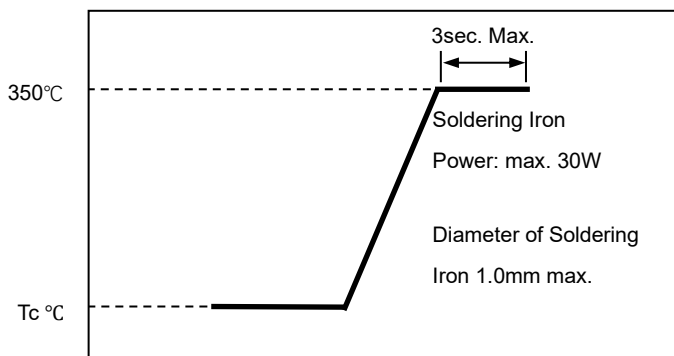
Peak temp: 260°C

Max time at Peak temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max

Iron Soldering Profile



Iron soldering power: Max. 30W

Pre-heating: 150°C/60sec.

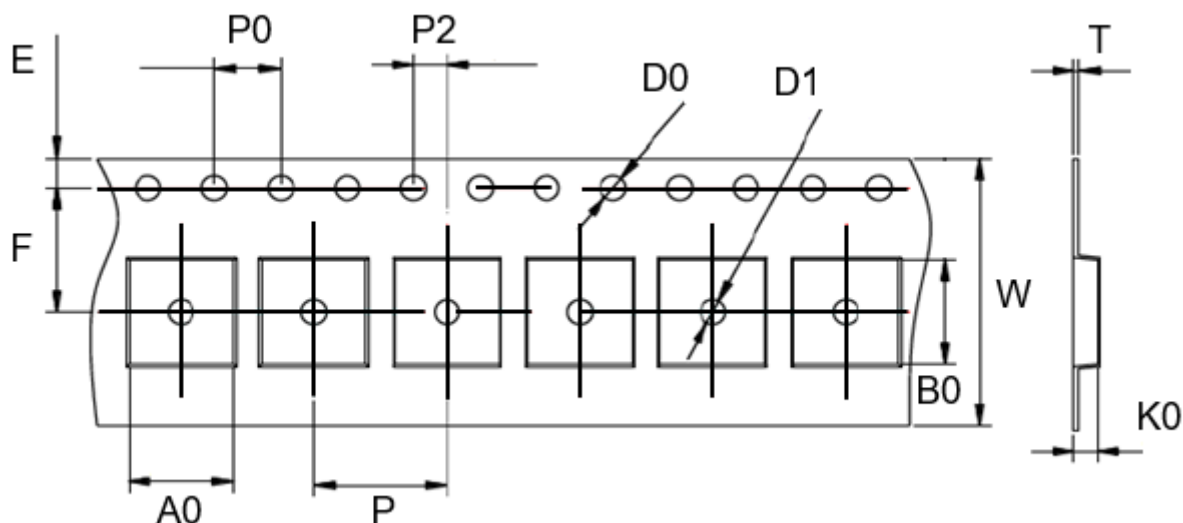
Soldering Tip temperature: 350°C Max.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

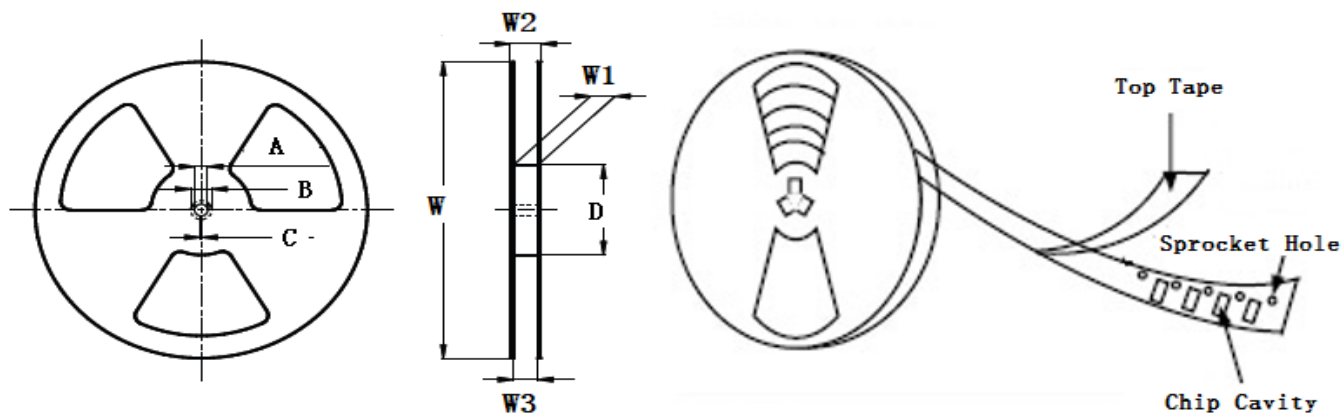
Max.1 times for iron soldering

■ Taping Dimensions(Unit:mm)



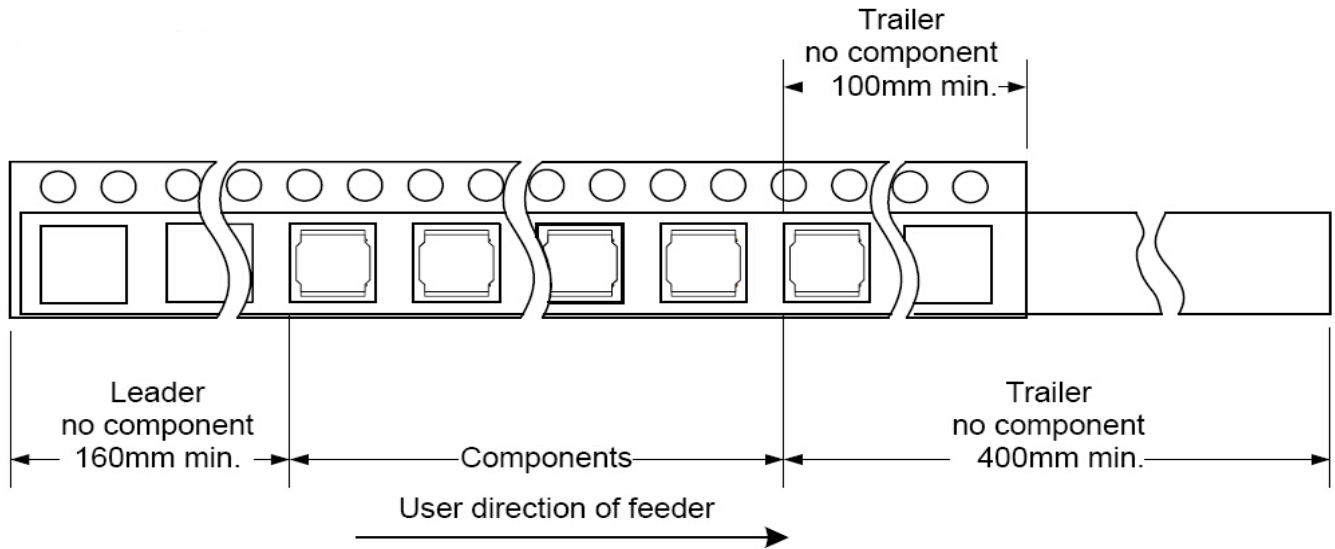
TYPE	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F	MPQ
YSPIT1508A	32.0 ±0.3	24.0 ±0.1	4.0 ±0.1	2.0 ±0.1	1.5 ±0.1	1.5 ±0.1	0.5 ±0.05	17.0 ±0.1	16.0 ±0.1	8.5 ±0.1	1.75 ±0.1	14.2 ±0.1	200

■ Reel Dimensions(Unit:mm)

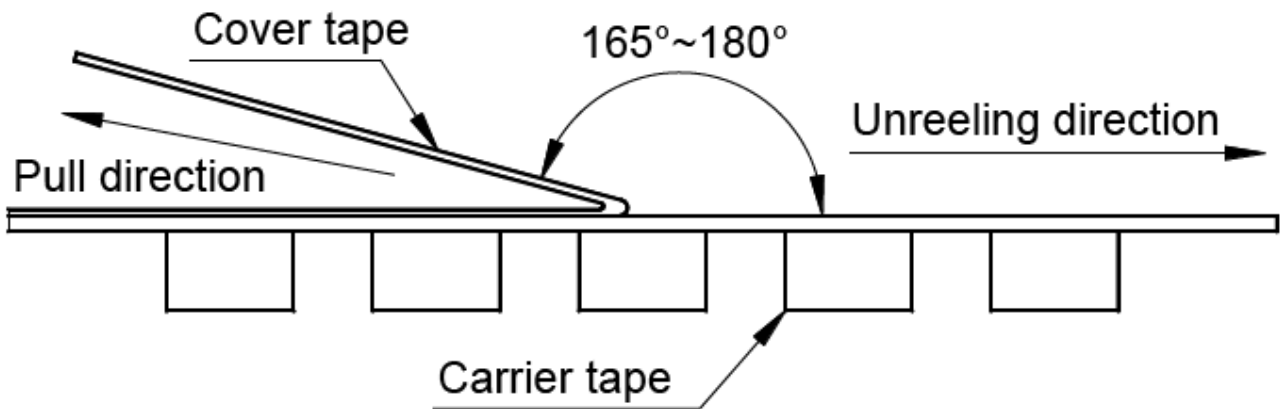


TYPE	W	W1	W2	W3	A	B	C	D
YSPIT1508A	330±2.0	32.4±2.0	38.4MAX	31.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	97±0.5

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.